MULTI-FUNCTIONAL TAPE FOR SEMICONDUCTOR PACKAGE AND A METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE USING THE SAME

ABSTRACT OF THE DISCLOSURE

Provided is a multifunctional tape for semiconductor packaging that can be used for a back-grinding process, a dicing process, a pickup process, and a die-attaching process at the same time. In particular, the multifunctional tape for a semiconductor package includes an ultraviolet-curable agent on an interface between an adhesive layer and a second bonding layer to form a first bonding layer that is hardened when the adhesive layer is hardened through exposure to ultraviolet light. Therefore, the adhesive layer imparts better peeling performance to the multi-functional tape. The multi-functional tape for a semiconductor package disclosed in this invention includes: the ultraviolet-curable adhesive layer formed on the surface of a base film, and the first and second bonding layers formed on the ultraviolet-curable adhesive layer.

Fig. 2